MC74LCX14

Low Voltage CMOS Hex Schmitt Inverter With 5 V-Tolerant Inputs

ON Semiconductor®

http://onsemi.com

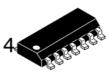
The MC74LCX14 is a high performance hex inverter with Schmitt−Trigger inputs operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers, while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX14 inputs to be safely driven from 5.0 V devices.

Pin configuration and function are the same as the MC74LCX04, but the inputs have hysteresis and, with its Schmitt trigger function, the LCX14 can be used as a line receiver which will receive slow input signals.

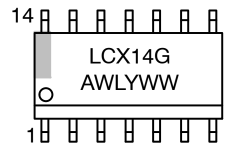
Features

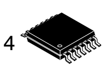
- Designed for 2.3 V to 3.6 V V_{CC} Operation
- 5.0 V Tolerant Inputs − Interface Capability with 5.0 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- Current Drive Capability is 24 mA at Source/Sink
- Pin and Function Compatible with Other Standard Logic Families
- ESD Performance: Human Body Model >2000 V
  Machine Model >100 V
- Chip Complexity: 41 Equivalent Gates
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

MARKING DIAGRAMS

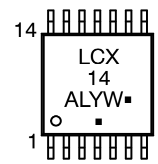


SOIC−14
D SUFFIX
CASE 751A





TSSOP−14
DT SUFFIX
CASE 948G



A	=	Assembly Location
L, WL	=	Wafer Lot
Y, YY	=	Year
W, WW	=	Work Week
G or ▪	=	Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

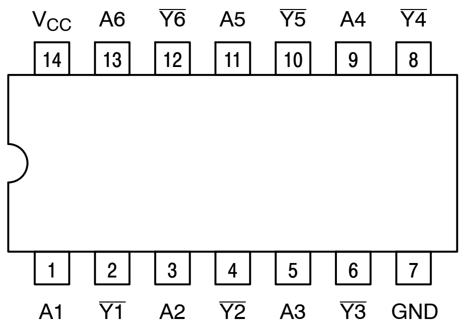


Figure 1. Pinout: 14−Lead (Top View)

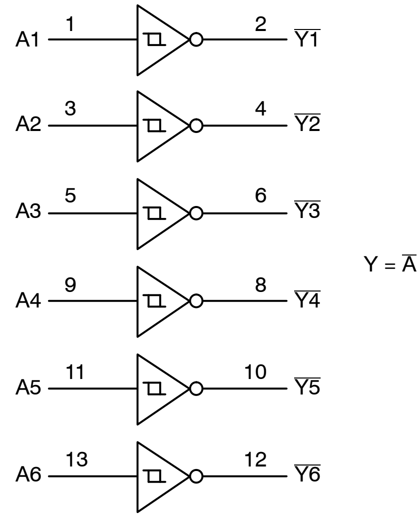


Figure 2. Logic Diagram

PIN NAMES

Pins	Function
An	Data Inputs
$\overline{Yn}$	Outputs

TRUTH TABLE

Inputs	Outputs
A	**$\overline{Y}$**
L	H
H	L

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Units
V_{CC}	DC Supply Voltage	−0.5 to +7.0		V
V_I	DC Input Voltage	$-0.5 \le V_I \le +7.0$		V
V_O	DC Output Voltage	$-0.5 \le V_O \le V_{CC} + 0.5$	Output in HIGH or LOW State. (Note 1)	V
I_{IK}	DC Input Diode Current	−50	V_I < GND	mA
I_{OK}	DC Output Diode Current	−50	V_O < GND	mA
		+50	$V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	±50		mA
I_{CC}	DC Supply Current Per Supply Pin	±100		mA
I_{GND}	DC Ground Current Per Ground Pin	±100		mA
T_{STG}	Storage Temperature Range	−65 to +150		°C
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Units
V_{CC}	Supply Voltage Operating Data Retention Only	 2.0 1.5	 2.5 to 3.3	 3.6 3.6	V
V_I	Input Voltage	0		5.5	V
V_O	Output Voltage (HIGH or LOW State)	0		V_{CC}	V
I_{OH}	HIGH Level Output Current V_{CC} = 3.0 V−3.6 V V_{CC} = 2.7 V−3.0 V V_{CC} = 2.3 V−2.7 V			 −24 −12 −8	mA
I_{OL}	LOW Level Output Current V_{CC} = 3.0 V−3.6 V V_{CC} = 2.7 V−3.0 V V_{CC} = 2.3 V−2.7 V			 +24 +12 +8	mA
T_A	Operating Free−Air Temperature	−40		+85	°C

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T_A = −40 to 85°C		Units
			Min	Max	
V_{T+}	Positive Input Threshold Voltage (Figure 3)	V_{CC} = 2.5 V V_{CC} = 3.0 V	0.9 1.2	1.7 2.2	V
V_{T-}	Negative Input Threshold Voltage (Figure 3)	V_{CC} = 2.5 V V_{CC} = 3.0 V	0.4 0.6	1.1 1.5	V
V_H	Input Hysteresis Voltage (Figure 3)	V_{CC} = 2.5 V V_{CC} = 3.0 V	0.3 0.4	1.0 1.2	V
V_{OH}	HIGH Level Output Voltage	2.3 V ≤ V_{CC} ≤ 3.6 V; I_{OL} = 100 μA	V_{CC} − 0.2		V
		V_{CC} = 2.3 V; I_{OH} = −8 mA	1.8		
		V_{CC} = 2.7 V; I_{OH} = −12 mA	2.2		
		V_{CC} = 3.0 V; I_{OH} = −18 mA	2.4		
		V_{CC} = 3.0 V; I_{OH} = −24 mA	2.2		
V_{OL}	LOW Level Output Voltage	2.3 V ≤ V_{CC} ≤ 3.6 V; I_{OL} = 100 μA		0.2	V
		V_{CC} = 2.3 V; I_{OL} = 8 mA		0.3	
		V_{CC} = 2.7 V; I_{OL} = 12 mA		0.4	
		V_{CC} = 3.0 V; I_{OL} = 16 mA		0.4	
		V_{CC} = 3.0 V; I_{OL} = 24 mA		0.55	
I_{OFF}	Power Off Leakage Current	V_{CC} = 0, V_{IN} = 5.5 V or V_{OUT} = 5.5 V		10	μA
I_{IN}	Input Leakage Current	V_{CC} = 3.6 V, V_{IN} = 5.5 V or GND		±5.0	μA
I_{CC}	Quiescent Supply Current	V_{CC} = 3.6 V, V_{IN} = 5.5 V or GND		10	μA
ΔI_{CC}	Increase in I_{CC} per Input	2.3 ≤ V_{CC} ≤ 3.6 V; V_{IH} = V_{CC} − 0.6 V		500	μA

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 2.5$ ns)

Symbol	Parameter	Waveform	Limits						Units
			$T_A = -40°C$ to $+85°C$						
			$V_{CC} = 3.3$ V ± 0.3 V		$V_{CC} = 2.7$ V		$V_{CC} = 2.5$ V ± 0.2 V		
			$C_L = 50$ pF		$C_L = 50$ pF		$C_L = 30$ pF		
			Min	Max	Min	Max	Min	Max	
t_{PLH} t_{PHL}	Propagation Delay Input to Output	1	1.5 1.5	6.5 6.5	1.5 1.5	7.5 7.5	1.5 1.5	7.8 7.8	ns
t_{OSHL} t_{OSLH}	Output−to−Output Skew (Note 2)			1.0 1.0					ns

2. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH−to−LOW (t_{OSHL}) or LOW−to−HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = +25°C$			Units
			Min	Typ	Max	
V_{OLP}	Dynamic LOW Peak Voltage (Note 3)	$V_{CC} = 3.3$ V, $C_L = 50$ pF, $V_{IH} = 3.3$ V, $V_{IL} = 0$ V $V_{CC} = 2.5$ V, $C_L = 30$ pF, $V_{IH} = 2.5$ V, $V_{IL} = 0$ V		0.8 0.6		V
V_{OLV}	Dynamic LOW Valley Voltage (Note 3)	$V_{CC} = 3.3$ V, $C_L = 50$ pF, $V_{IH} = 3.3$ V, $V_{IL} = 0$ V $V_{CC} = 2.5$ V, $C_L = 30$ pF, $V_{IH} = 2.5$ V, $V_{IL} = 0$ V		−0.8 −0.6		V

3. Number of outputs defined as “n”. Measured with “n−1” outputs switching from HIGH−to−LOW or LOW−to−HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = 3.3$ V, $V_I = 0$ V or V_{CC}	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3$ V, $V_I = 0$ V or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance	10 MHz, $V_{CC} = 3.3$ V, $V_I = 0$ V or V_{CC}	25	pF

ORDERING INFORMATION

Device	Package	Shipping†
MC74LCX14DG	SOIC−14 (Pb−Free)	55 Units / Rail
MC74LCX14DR2G	SOIC−14 (Pb−Free)	2500 Tape & Reel
MC74LCX14DTG	TSSOP−14 (Pb−Free)	96 Units / Rail
MC74LCX14DTR2G	TSSOP−14 (Pb−Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

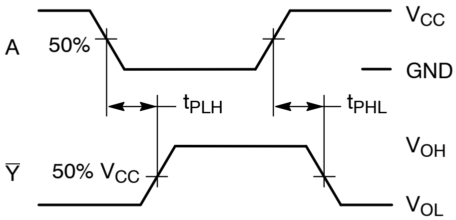


Figure 3. Switching Waveforms

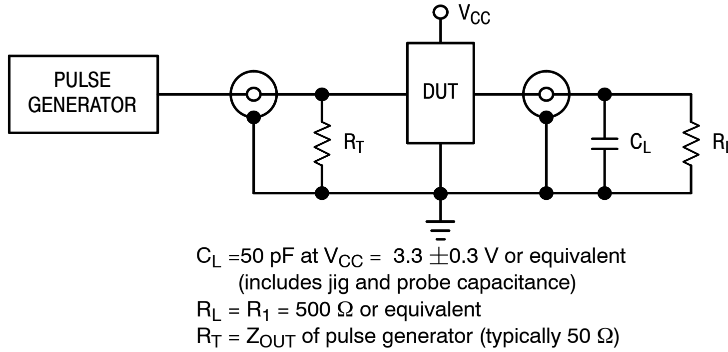


Figure 4. Test Circuit

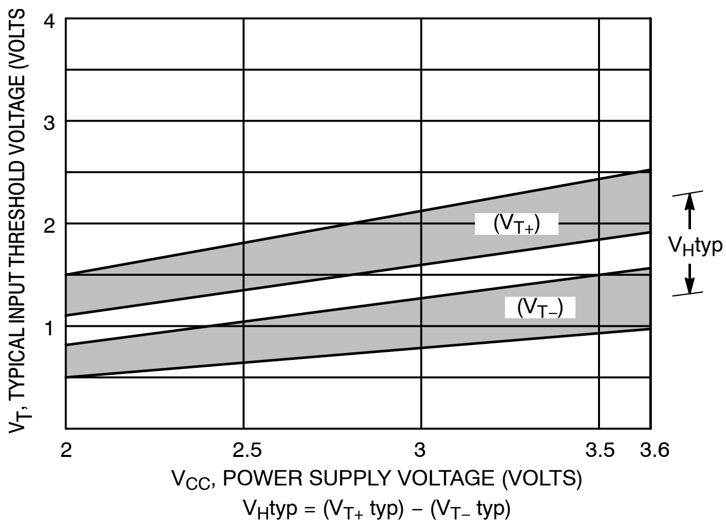


Figure 5. Typical Input Threshold, V_{T+}, V_{T-} versus Power Supply Voltage

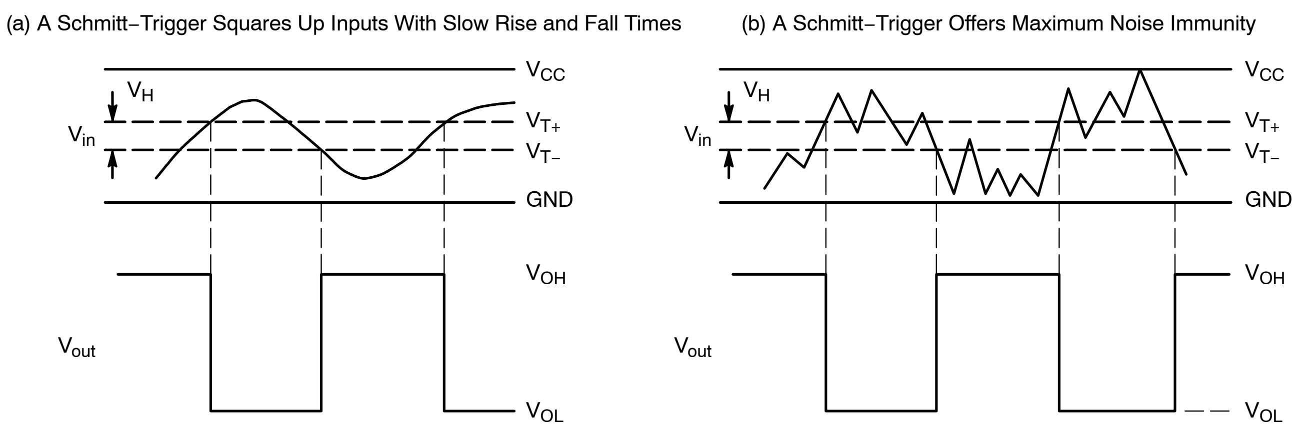


Figure 6. Typical Schmitt−Trigger Applications

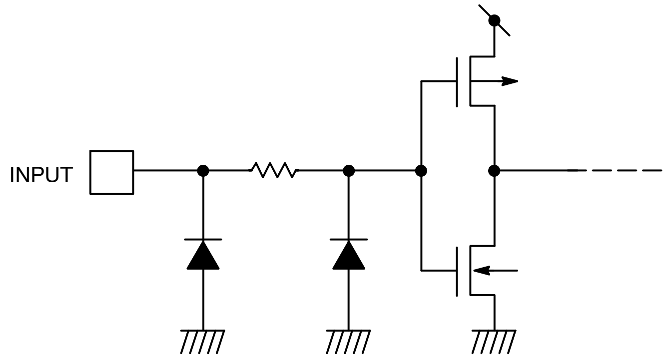
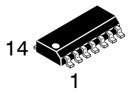


Figure 7. Input Equivalent Circuit



SCALE 1:1

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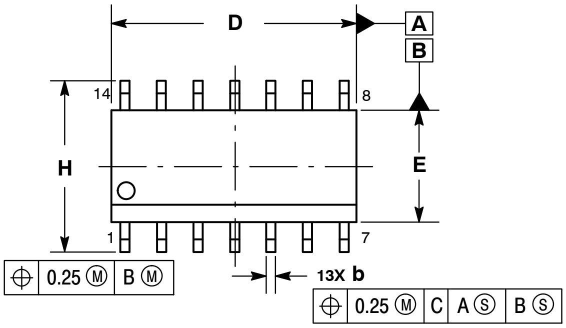
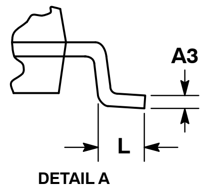
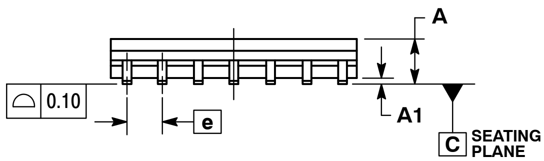
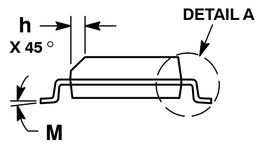
ISSUE L

DATE 03 FEB 2016





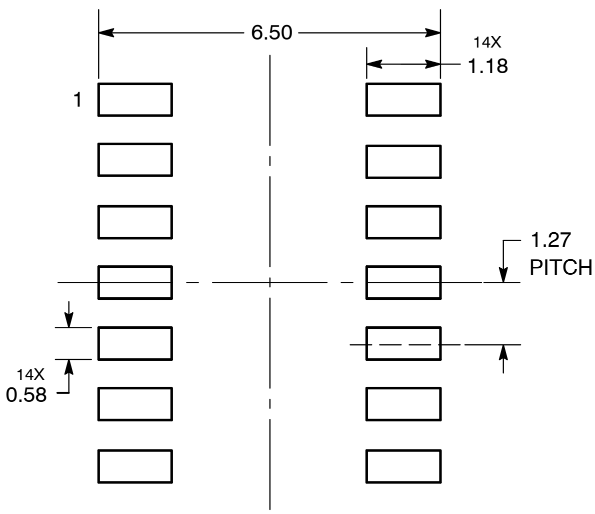




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7 °	0 °	7 °

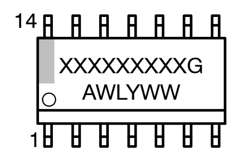
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42565B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	SOIC−14 NB	PAGE 1 OF 2

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ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
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For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales

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